### **INTEGRATED CIRCUITS**

# DATA SHEET



## 74ABT2952

Octal registered transceiver (3-State)

Product specification
Supersedes data of 1995 Jun 15
IC23 Data Handbook

1998 Feb 11





### Octal registered transceiver (3-State)

74ABT2952

#### **FEATURES**

- 8-bit registered transceiver
- Independent registers for A and B buses
- Output capability: +64mA/-32mA
- Latch-up protection exceeds 500mA per JEDEC Std 17
- ESD protection exceeds 2000V per MIL STD 883 Method 3015 and 200V per Machine Model
- Power-up 3-State
- Power-up reset
- Live insertion/extraction permitted

#### **DESCRIPTION**

The 74ABT2952 high-performance BiCMOS device combines low static and dynamic power dissipation with high speed and high output drive.

The 74ABT2952 device is an 8-bit registered transceiver. Two 8-bit back-to-back registers store data flowing in both directions between two bidirectional buses. Data applied to the inputs is entered and stored on the rising edge of the Clock (CPXX) provided that the Clock Enable (CEXX) is Low. The data is then present at the 3-State output buffers, but is only accessible when the Output Enable (OEXX) is Low. Data flow from A inputs to B outputs is the same as for B inputs to A outputs.

#### **QUICK REFERENCE DATA**

SYMBOL	PARAMETER	PARAMETER CONDITIONS  T <sub>amb</sub> = 25°C; GND = 0V				
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation delay CPBA to An or CPAB to Bn	$C_L = 50pF; V_{CC} = 5V$	5.7	ns		
C <sub>IN</sub>	Input capacitance	V <sub>I</sub> = 0V or V <sub>CC</sub>	4	pF		
C <sub>I/O</sub>	I/O capacitance	Outputs disabled; $V_O = 0V$ or $V_{CC}$	7	pF		
I <sub>CCZ</sub>	Total supply current	Outputs disabled; V <sub>CC</sub> =5.5V	110	μΑ		

#### **ORDERING INFORMATION**

PACKAGES	TEMPERATURE RANGE	OUTSIDE NORTH AMERICA	NORTH AMERICA	DWG NUMBER
24-Pin Plastic DIP	-40°C to +85°C	74ABT2952 N	74ABT2952 N	SOT222-1
24-Pin plastic SO	-40°C to +85°C	74ABT2952 D	74ABT2952 D	SOT137-1
24-Pin Plastic SSOP Type II	-40°C to +85°C	74ABT2952 DB	74ABT2952 DB	SOT340-1
24-Pin Plastic TSSOP Type I	-40°C to +85°C	74ABT2952 PW	7ABT2952PW DH	SOT355-1

#### **PIN CONFIGURATION**

B7 1	24	V <sub>CC</sub>
B6 2	23	A7
B5 3	22	A6
B4 4	21	A5
B3 5	20	A4
B2 6	19	A3
B1 7	18	A2
B0 8	17	A1
OEAB 9	16	A0
CPAB 10	15	OEBA
CEAB 11	14	СРВА
GND 12	13	CEBA
	SA00114	1

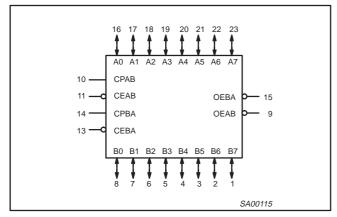
#### **PIN DESCRIPTION**

PIN NUMBER	SYMBOL	NAME AND FUNCTION
10, 14	CPAB / CPBA	Clock input A to B / Clock input B to A
11, 13	CEAB / CEBA	Clock enable input A to B / Clock enable input B to A
16, 17, 18, 19, 20, 21, 22, 23	A0 – A7	Data inputs/outputs (A side)
1, 2, 3, 4, 5, 6, 7, 8	B0 – B7	Data outputs/outputs (B side)
9, 15	OEAB / OEBA	Output enable inputs
12	GND	Ground (0V)
24	V <sub>CC</sub>	Positive supply voltage

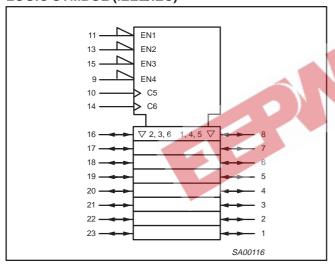
### Octal registered transceiver (3-State)

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#### **LOGIC SYMBOL**



#### LOGIC SYMBOL (IEEE/IEC)



#### **FUNCTION TABLE for Register An or Bn**

II.	NPUTS		INTERNAL	OPERATING
An or Bn	СРХХ	CEXX	Q	MODE
Х	Х	Н	NC	Hold data
L H	<b>↑</b>	L L	L H	Load data

H = High voltage level

L = Low voltage level

↑ = Low–to–High transition

X = Don't care XX = AB or BA

NC=No change

#### **FUNCTION TABLE for Output Enable**

INPUTS	INTERNAL	An or Bn	OPERATING
OEXX	Q	OUTPUTS	MODE
Н 36с	Х	Z	Disable outputs
老书"	H	L H	Enable outputs

H = High voltage level

L = Low voltage level

X = Don't care

XX = AB or BAZ = High impedance "off" state

#### **ABSOLUTE MAXIMUM RATINGS<sup>1, 2</sup>**

				_
SYMBOL	PARAMETER	CONDITIONS	RATING	UNIT
V <sub>CC</sub>	DC supply voltage		-0.5 to +7.0	V
I <sub>IK</sub>	DC input diode current	V <sub>I</sub> < 0	-18	mA
VI	DC input voltage <sup>3</sup>		-1.2 to +7.0	V
I <sub>OK</sub>	DC output diode current	V <sub>O</sub> < 0	<b>-</b> 50	mA
V <sub>OUT</sub>	DC output voltage <sup>3</sup>	output in Off or High state	−0.5 to +5.5	V
I <sub>OUT</sub>	DC output current	output in Low state	128	mA
T <sub>stg</sub>	Storage temperature range		-65 to 150	°C

#### NOTES:

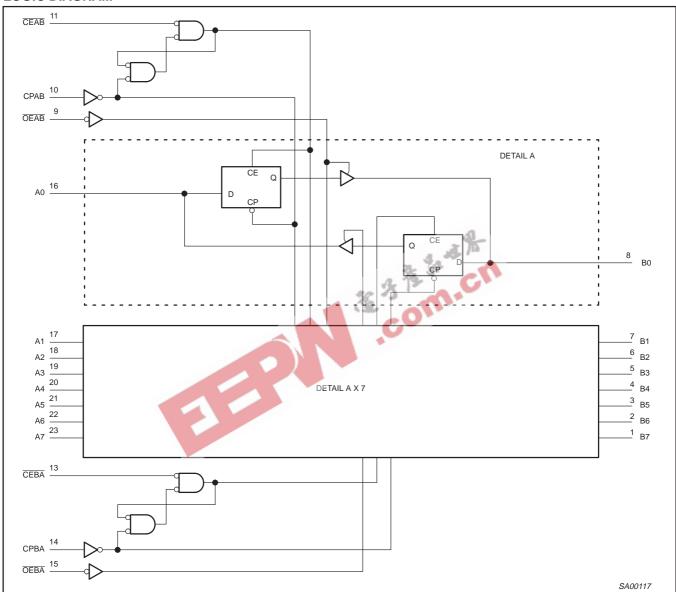
- Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the
  device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to
  absolute-maximum-rated conditions for extended periods may affect device reliability.
- 2. The performance capability of a high-performance integrated circuit in conjunction with its thermal environment can create junction temperatures which are detrimental to reliability. The maximum junction temperature of this integrated circuit should not exceed 150°C.

3. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

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#### **LOGIC DIAGRAM**



#### **RECOMMENDED OPERATING CONDITIONS**

CVMDOL	DADAMETED	LIM	ITS	UNIT	
SYMBOL	PARAMETER	Min	Max	ONIT	
V <sub>CC</sub>	DC supply voltage	4.5	5.5	V	
VI	Input voltage	0	V <sub>CC</sub>	V	
V <sub>IH</sub>	High-level input voltage	2.0		V	
$V_{IL}$	Low-level Input voltage		0.8	V	
I <sub>OH</sub>	High-level output current		-32	mA	
I <sub>OL</sub>	Low-level output current		64	mA	
Δt/Δν	Input transition rise or fall rate	0	10	ns/V	
T <sub>amb</sub>	Operating free-air temperature range	-40	+85	°C	

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#### DC ELECTRICAL CHARACTERISTICS

						LIMITS			
SYMBOL	PARAM	ETER	TEST CONDITIONS	Tai	$T_{amb} = +25^{\circ}C$			-40°C 85°C	UNIT
				Min	Тур	Max	Min	Max	
V <sub>IK</sub>	Input clamp volt	age	$V_{CC} = 4.5V; I_{IK} = -18mA$		-0.9	-1.2		-1.2	V
			$V_{CC} = 4.5V$ ; $I_{OH} = -3mA$ ; $V_I = V_{IL}$ or $V_{IH}$	2.5	3.5		2.5		V
V <sub>OH</sub>	V <sub>OH</sub> High-level output voltage		$V_{CC} = 5.0V$ ; $I_{OH} = -3mA$ ; $V_I = V_{IL}$ or $V_{IH}$	3.0	4.0		3.0		V
			$V_{CC} = 4.5V$ ; $I_{OH} = -32mA$ ; $V_I = V_{IL}$ or $V_{IH}$	2.0	2.6		2.0		V
V <sub>OL</sub>	Low-level output voltage		$V_{CC} = 4.5V$ ; $I_{OL} = 64mA$ ; $V_I = V_{IL}$ or $V_{IH}$		0.42	0.55		0.55	V
V <sub>RST</sub>	Power-up output low voltage <sup>3</sup>		$V_{CC} = 5.5V$ ; $I_O = 1mA$ ; $V_I = GND$ or $V_{CC}$		0.13	0.55		0.55	V
I <sub>I</sub>	Input leakage Control pins current Data pins		$V_{CC} = 5.5V; V_I = GND \text{ or } 5.5V$	40	±0.01	±1.0		±1.0	μΑ
			$V_{CC} = 5.5V; V_{I} = GND \text{ or } 5.5V$	10	5	100		100	μΑ
I <sub>OFF</sub>	Power-off leakage current		$V_{CC} = 0.0V$ ; $V_O = 4.5V$ ; $V_I = 0.0V$ or 5.5V	C	±5.0	±100		±100	μΑ
I <sub>PU</sub> /I <sub>PD</sub>	Power-up/down output current <sup>4</sup>	3-State	$V_{CC}$ = 2.1V; $V_{O}$ = 0.5V; $V_{I}$ = GND or $V_{CC}$ ; $V_{OE}$ = Don't care		±5.0	±50		±50	μА
I <sub>OZH</sub>	3-State output H	High current	$V_{CC}$ = 5.5V; $V_O$ = 2.7V; $V_I$ = $V_{IL}$ or $V_{IH}$		5.0	50		50	μΑ
I <sub>OZL</sub>	3-State output L	ow current	$V_{CC}$ = 5.5V; $V_O$ = 0.5V; $V_I$ = $V_{IL}$ or $V_{IH}$		-5.0	-50		-50	μΑ
I <sub>CEX</sub>	Output High lea	kage current	$V_{CC} = 5.5V$ ; $V_O = 5.5V$ ; $V_I = GND$ or $V_{CC}$		5.0	50		50	μΑ
Io	Output current <sup>1</sup>		$V_{CC} = 5.5V; V_{O} = 2.5V$	-50	-80	-180	-50	-180	mA
Іссн		72	$V_{CC} = 5.5V$ ; Outputs High, $V_{I} = GND$ or $V_{CC}$		110	250		250	μΑ
I <sub>CCL</sub>	Quiescent supply current		$V_{CC}$ = 5.5V; Outputs Low, $V_I$ = GND or $V_{CC}$		20	30		30	mA
I <sub>CCZ</sub>			$V_{CC}$ = 5.5V; Outputs 3-State; $V_{I}$ = GND or $V_{CC}$		110	250		250	μА
Δl <sub>CC</sub>	Additional supplinput pin <sup>2</sup>	ly current per	$V_{CC}$ = 5.5V; one input at 3.4V, other inputs at $V_{CC}$ or GND		0.3	1.5		1.5	mA

- Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
   This is the increase in supply current for each input at 3.4V.
   For valid test results, data must not be loaded into the flip-flops (or latches) after applying the power.
   This parameter is valid for any V<sub>CC</sub> between 0V and 2.1V, with a transition time of up to 10msec. From V<sub>CC</sub> = 2.1V to V<sub>CC</sub> = 5V ± 10% a transition time of up to 100µsec is permitted.

#### **AC CHARACTERISTICS**

GND = 0V;  $t_R = t_F$  = 2.5ns;  $C_L$  = 50pF,  $R_L$  = 500 $\Omega$ 

					LIMIT	rs		
SYMBOL	PARAMETER	WAVEFORM	T <sub>a</sub>	<sub>imb</sub> = +25° CC = +5.0°	C V	T <sub>amb</sub> = -40° V <sub>CC</sub> = +5.	°C to +85°C .0V ±0.5V	MHz ns
			Min	Тур	Max	Min	Max	
f <sub>MAX</sub>	Maximum clock frequency	1	150	250		150		MHz
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation delay CPBA to An, CPAB to Bn	1	2.0 2.5	3.2 3.8	6.6 7.2	2.0 2.5	7.6 8.2	ns
t <sub>PZH</sub> t <sub>PZL</sub>	Output enable time OEBA to An, OEAB to Bn	3 4	1.0 2.2	3.2 4.4	4.8 6.2	1.0 2.2	5.8 7.5	ns
t <sub>PHZ</sub> t <sub>PLZ</sub>	Output disable time OEBA to An, OEAB to Bn	3 4	2.0 1.5	3.6 2.8	7.6 7.1	2.0 1.5	8.1 7.6	ns

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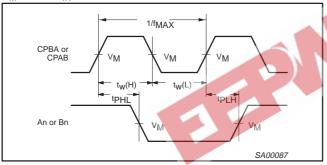
74ABT2952

#### **AC SETUP REQUIREMENTS**

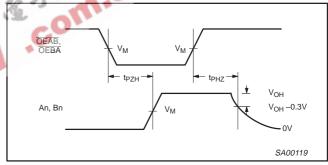
					LIMITS			
SYMBOL	PARAMETER	WAVEFORM	T <sub>amb</sub> = V <sub>CC</sub> =	+25°C +5.0V	$T_{amb} = -40^{\circ}\text{C to } +85^{\circ}\text{C}$ $V_{CC} = +5.0\text{V } \pm 0.5\text{V}$	UNIT		
			Min	Тур	Min	ns ns		
t <sub>S</sub> (H) t <sub>S</sub> (L)	Setup time An to CPAB or Bn to CPBA	2	4.5 3.5	2.2 1.6	4.5 3.5	ns		
t <sub>h</sub> (H) t <sub>h</sub> (L)	Hold time An to CPAB or Bn to CPBA	2	0.0 0.0	-0.8 -1.4	0.0 0.0	ns		
t <sub>s</sub> (H) t <sub>s</sub> (L)	Setup time CEAB to CPAB, CEBA to CPBA	2	4.0 3.0	0.8 0.8	4.0 3.0	ns		
t <sub>h</sub> (H) t <sub>h</sub> (L)	Hold time CEAB to CPAB, CEBA to CPBA	2	0.0 0.0	-0.7 -0.7	0.0 0.0	ns		
t <sub>w</sub> (H) t <sub>w</sub> (L)	CPAB or CPBA pulse width, High or Low	1	3.0 3.5	0.8 0.9	3.0 3.5	ns		

#### **AC WAVEFORMS**

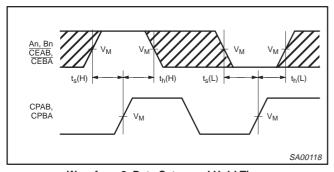
 $V_M = 1.5V$ ,  $V_{IN} = GND$  to 3.0V



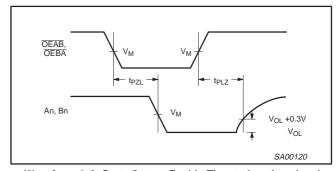
Waveform 1. Propagation Delay, Clock Input to Output, Clock Pulse Width, and Maximum Clock Frequency



Waveform 3. 3-State Output Enable Time to High Level and Output Disable Time from High Level



Waveform 2. Data Setup and Hold Times

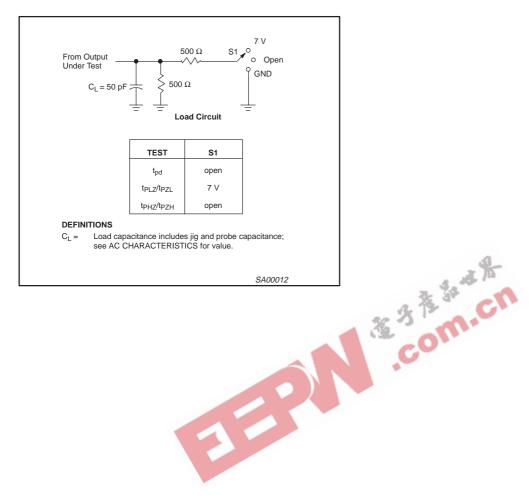


Waveform 4. 3–State Output Enable Time to Low Level and Output Disable Time from Low Level

#### **TEST CIRCUIT AND WAVEFORMS**

### Octal registered transceiver (3-State)

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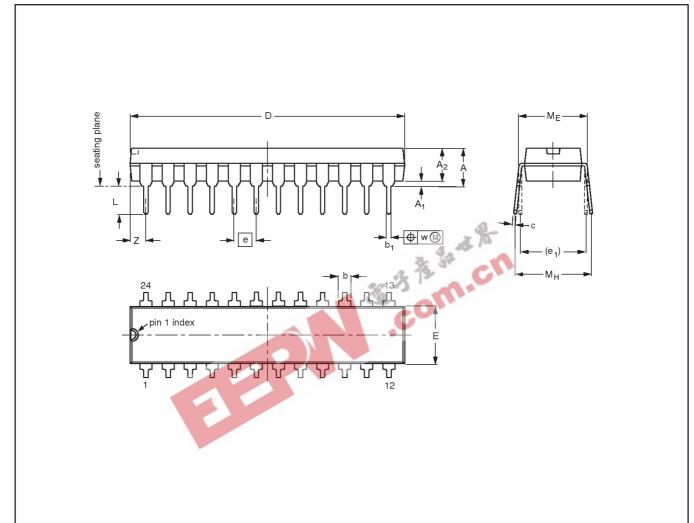
7

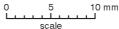
### Octal registered transceiver (3-State)

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#### DIP24: plastic dual in-line package; 24 leads (300 mil)

SOT222-1





#### DIMENSIONS (millimetre dimensions are derived from the original inch dimensions)

	UNIT	A max.	A <sub>1</sub> min.	A <sub>2</sub> max.	b	b <sub>1</sub>	С	D <sup>(1)</sup>	E <sup>(1)</sup>	е	e <sub>1</sub>	L	ME	Мн	w	Z <sup>(1)</sup> max.
	mm	4.70	0.38	3.94	1.63 1.14	0.56 0.43	0.36 0.25	31.9 31.5	6.73 6.48	2.54	7.62	3.51 3.05	8.13 7.62	10.03 7.62	0.25	2.05
i	nches	0.185	0.015	0.155	0.064 0.045	0.022 0.017	0.014 0.010	1.256 1.240	0.265 0.255	0.100	0.300	0.138 0.120	0.32 0.30	0.395 0.300	0.01	0.081

#### Note

1. Plastic or metal protrusions of 0.01 inches maximum per side are not included.

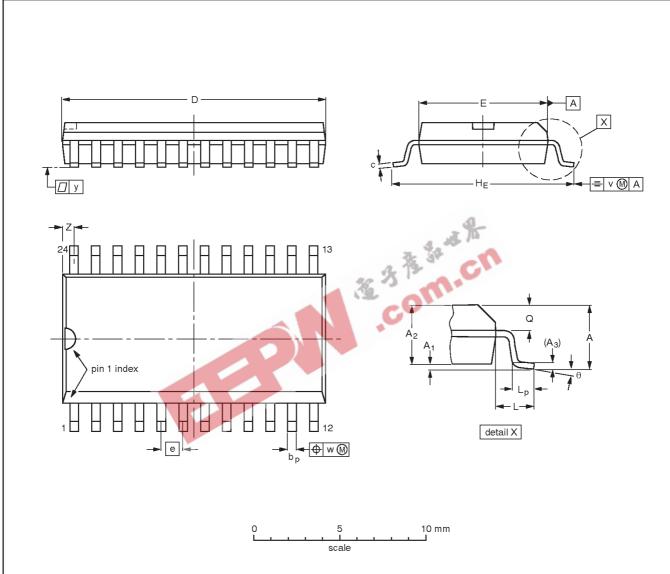
OUTLINE		EUROPEAN	ISSUE DATE				
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE	
SOT222-1		MS-001AF				95-03-11	

### Octal registered transceiver (3-State)

74ABT2952

#### SO24: plastic small outline package; 24 leads; body width 7.5 mm

SOT137-1



#### DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	А3	bр	С	D <sup>(1)</sup>	E <sup>(1)</sup>	е	HE	L	Lp	Q	٧	w	у	z <sup>(1)</sup>	θ
mm	2.65	0.30 0.10	2.45 2.25	0.25	0.49 0.36	0.32 0.23	15.6 15.2	7.6 7.4	1.27	10.65 10.00	1.4	1.1 0.4	1.1 1.0	0.25	0.25	0.1	0.9 0.4	8°
inches	0.10	0.012 0.004	0.096 0.089	0.01	0.019 0.014	0.013 0.009	0.61 0.60	0.30 0.29	0.050	0.419 0.394	0.055	0.043 0.016		0.01	0.01	0.004	0.035 0.016	0°

#### Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

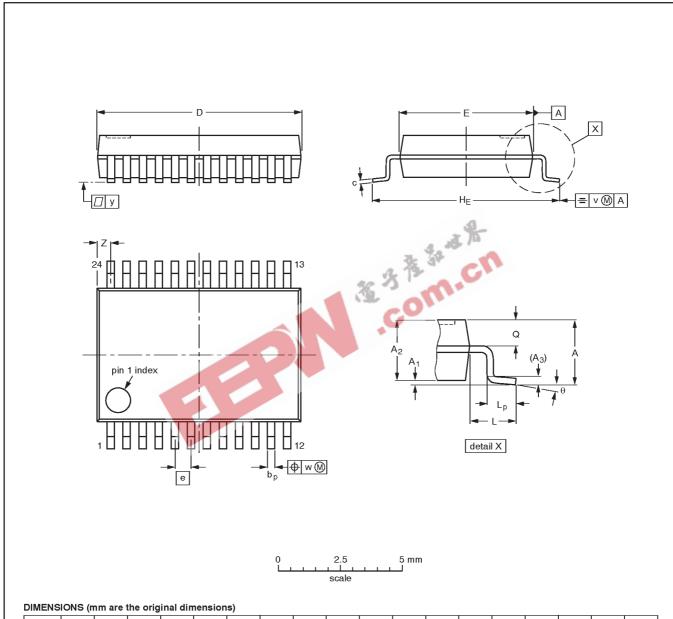
OUTLINE		EUROPEAN	ISSUE DATE				
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE	
SOT137-1	075E05	MS-013AD				<del>-95-01-24</del> 97-05-22	

### Octal registered transceiver (3-State)

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#### SSOP24: plastic shrink small outline package; 24 leads; body width 5.3 mm

SOT340-1



UNIT	A max.	Α1	A <sub>2</sub>	A <sub>3</sub>	bр	O	D <sup>(1)</sup>	E <sup>(1)</sup>	е	HE	L	Lp	Q	v	w	у	Z <sup>(1)</sup>	θ
mm	2.0	0.21 0.05	1.80 1.65	0.25	0.38 0.25	0.20 0.09	8.4 8.0	5.4 5.2	0.65	7.9 7.6	1.25	1.03 0.63	0.9 0.7	0.2	0.13	0.1	0.8 0.4	8° 0°

#### Note

1. Plastic or metal protrusions of 0.20 mm maximum per side are not included.

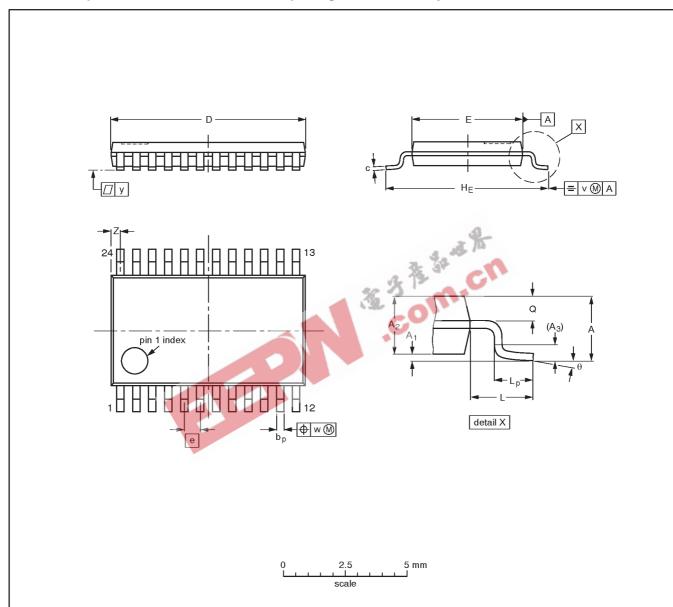
OUTLINE		EUROPEAN	ISSUE DATE			
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUEDATE
SOT340-1		MO-150AG				<del>93-09-08</del> 95-02-04

### Octal registered transceiver (3-State)

74ABT2952

TSSOP24: plastic thin shrink small outline package; 24 leads; body width 4.4 mm

SOT355-1



#### DIMENSIONS (mm are the original dimensions)

UNIT	A max.	Α1	A <sub>2</sub>	A <sub>3</sub>	рb	С	D <sup>(1)</sup>	E <sup>(2)</sup>	е	HE	L	Lp	Q	v	w	у	Z <sup>(1)</sup>	θ
mm	1.10	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	7.9 7.7	4.5 4.3	0.65	6.6 6.2	1.0	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.5 0.2	8° 0°

#### Notes

- 1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
- 2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE		EUROPEAN	ISSUE DATE			
VERSION	IEC	JEDEC	EIAJ	PROJECTION	1990E DATE	
SOT355-1		MO-153AD			<del>-93-06-16-</del> 95-02-04	

### Octal registered transceiver (3-State)

74ABT2952

#### Data sheet status

Data sheet status	Product status	Definition [1]
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
Preliminary specification	Qualification	This data sheet contains preliminary data, and supplementary data will be published at a later date.  Philips Semiconductors reserves the right to make chages at any time without notice in order to improve design and supply the best possible product.
Product specification	Production	This data sheet contains final specifications. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.

<sup>[1]</sup> Please consult the most recently issued datasheet before initiating or completing a design.

#### **Definitions**

**Short-form specification** — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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print code Date of release: 05-96

Document order number: 9397-750-03479

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